

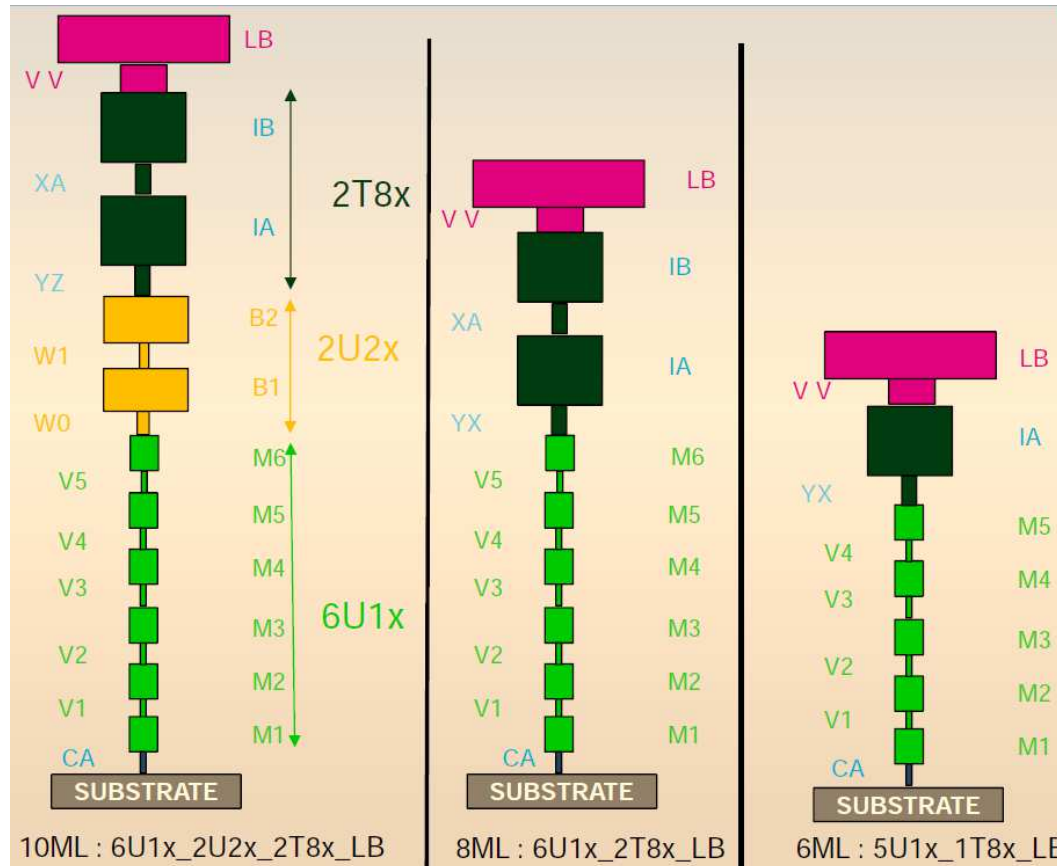
FD-SOI FOR RF IC DESIGN

SITRI – LETI Workshop | Mercier Eric | 08 september 2016



UTBB 28 nm FD-SOI : RF DIRECT BENEFITS (1/2)

- 3 back-end options available



- Routing possible on the AluCap level → no restriction vs. 0.7 % in 65 nm

UTBB 28 nm FD-SOI : RF DIRECT BENEFITS (2/2)

- Capacitors

Capacitor	Density (Typical)	Observation
egncap	10.1fF / μm^2	GO2 device (thick gate oxide)
CMOM - M1 to M5 (max)	6.45fF / μm^2	Space(finger) = Width(finger) between 50 and 100nm $V_{\text{max}} = 1.1\text{V}$ for $S=W < 80 \text{ nm}$ $V_{\text{max}} = 1.8\text{V}$ for $S=W > 80 \text{ nm}$
CMIM	16.2fF / μm^2	process option : add 3 masks Total area max = 24.6mm ² $V_{\text{max}} = 1.155\text{V}$
lvtnfet ($V_g = 1\text{V} \dots V_x = 0\text{V}$)	~18fF / μm^2	Used as loop filter or supply bypass capacitor Depends on the config. Low capacitance for low voltage.
lvtpfet ($V_b = 1\text{V} \dots V_x = 0\text{V}$)	~17fF / μm^2	Used as loop filter or supply bypass capacitor Depends on the config. Low capacitance for low voltage.

- Very good density / less parasitics to substrate
- Interesting MIM capacitor quality factor
- All required devices for RF exist in FD-SOI

UTBB-FDSOI 28nm FOR ULP RF (1/4)

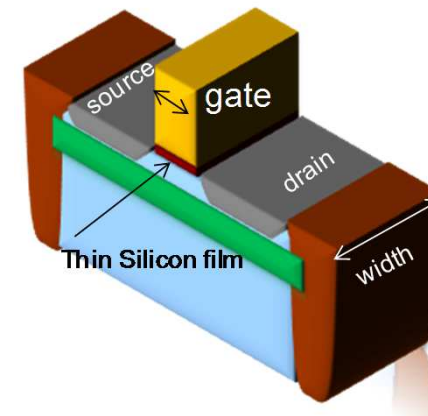
ACTIVE DEVICES PERFORMANCE AND COMPARISON

- **No channel doping : better gain compare to bulk**
 - At 0.18 μm gate length, the analog gain G_m/G_d in weak inversion in FD-SOI 28nm is higher than the 180 nm CMOS

	0.18CMOS	28nmBulk	FDSOI28nm
G_m/G_d	50	25	75

- At 1 μm gate length, the G_m/G_d on FDSOI is 6 time larger than the CMOS 28 nm bulk

	28nmBulk	FDSOI28nm
G_m/G_d	50	300

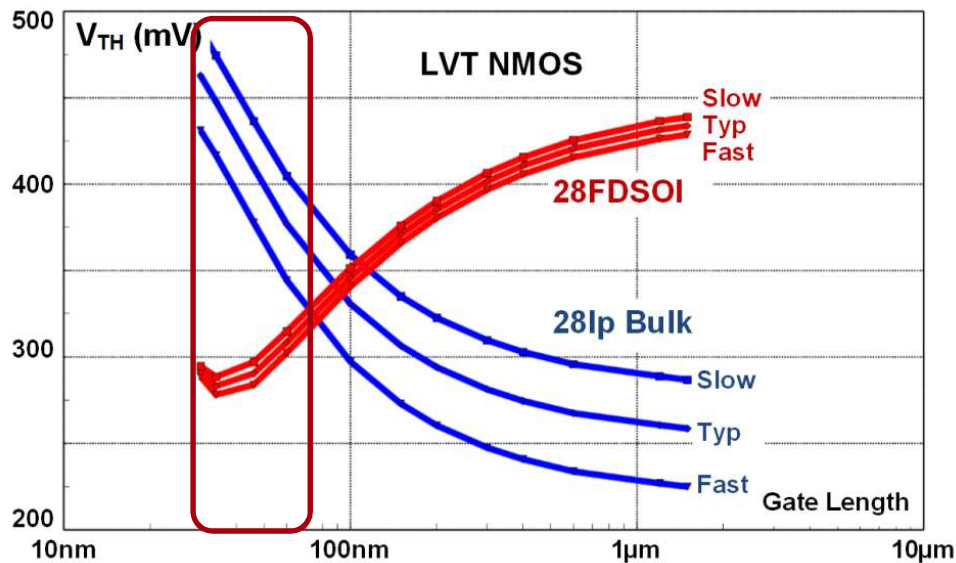


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UTBB-FDSOI 28nm FOR ULP RF (2/4)

HIGH SPEED ANALOG PERFORMANCE

- **Lower V_{th} , less variability**
 - Design at Low Power supply
 - High dynamic range
 - With respect to V_{DD} versus V_{th}
 - Analog compatible minimum gate lengths



- **Reduced S/D capacitances**
 - Increased comparator BW
 - Faster logic
 - Reduced switch parasitic
 - Less Power consumption

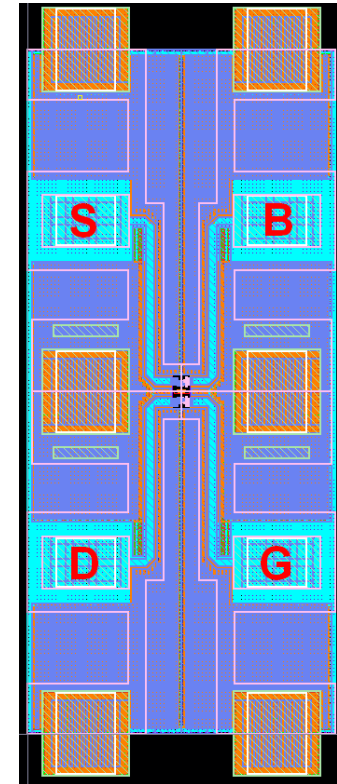
UTBB-FDSOI 28nm FOR ULP RF (3/4)

HIGH RF PERFORMANCES ON BOTH FRONT- & BACK-GATE

- **Front Gate FT : faster transistor even at low power supply**
 - FT: 300 GHz @ 1 volts V_{DD}
 - FT: 150 GHz @ 0.3 Volts V_{DD}

MEASUREMENTS DONE at LETI

- **Back gate useful for RF → simple design**
 - FT: 80 GHz @ 1 volts V_{DD}
 - FT: 40 GHz @ 0.3 volts V_{DD}

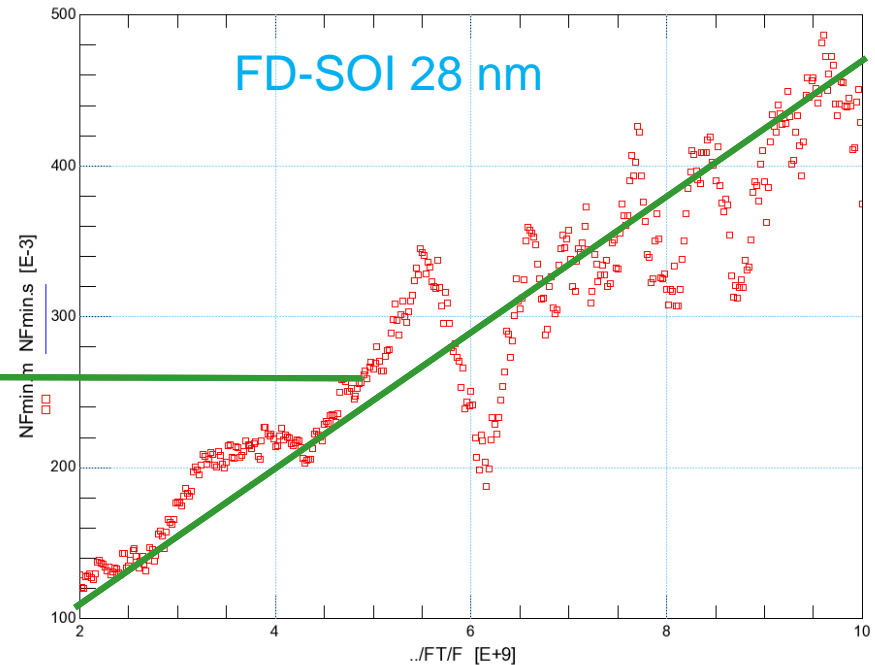
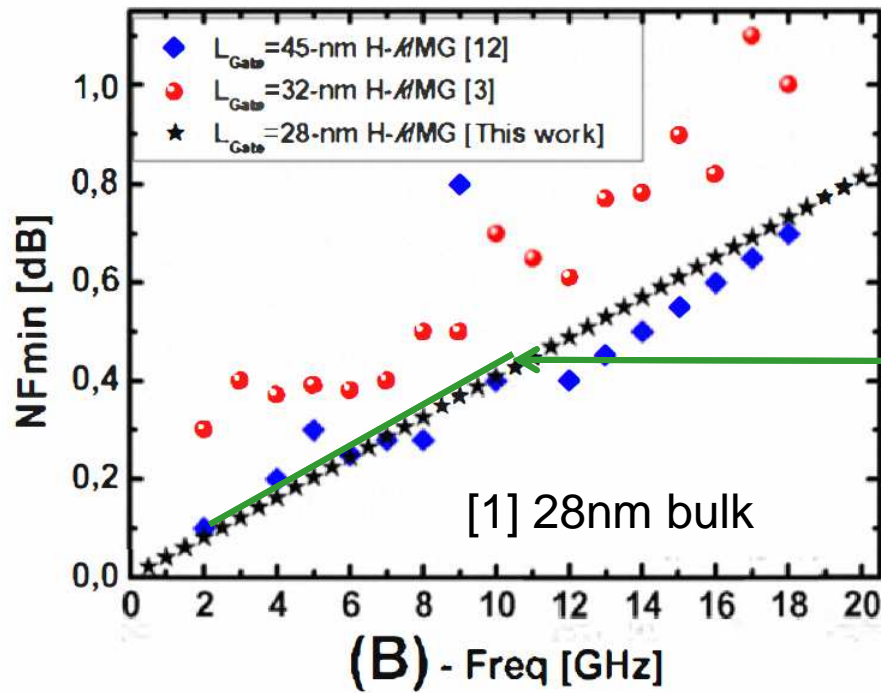


UTBB-FDSOI 28nm FOR ULP RF (4/4)

LOW NOISE PERFORMANCE

- $NF_{min} \approx 0.2\text{dB}$ ($F = 2\text{ GHz}$), $\approx 0.4\text{dB}$ ($F = 10\text{ GHz}$)
- Noise performances similar to 28nm Bulk

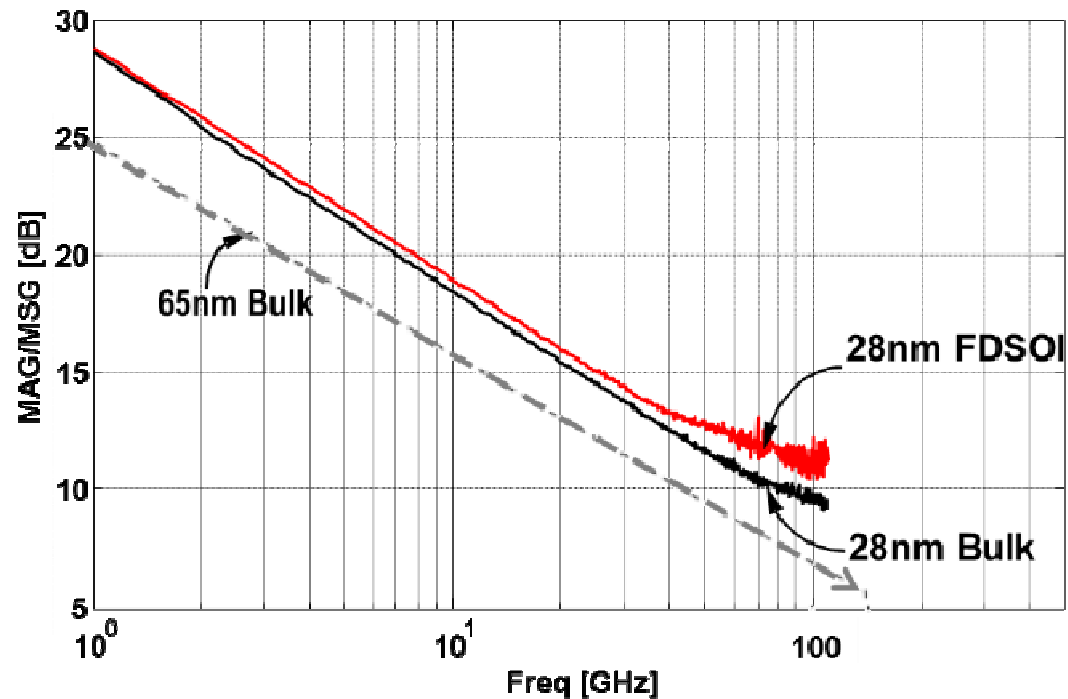
$I_{ds}=135\text{ mA/mm}$, $L_g=30\text{nm}$



[1] Y. Tagro et al "RF Noise Investigation in High-k/Metal Gate 28-nm CMOS Transistors" IEEE IMS, june 2012

UTBB-FDSOI 28nm : FROM RF TO mmW

- Active devices performance and comparison (RF)
 - Higher Gain than CMOS 28 nm & 65nm technology

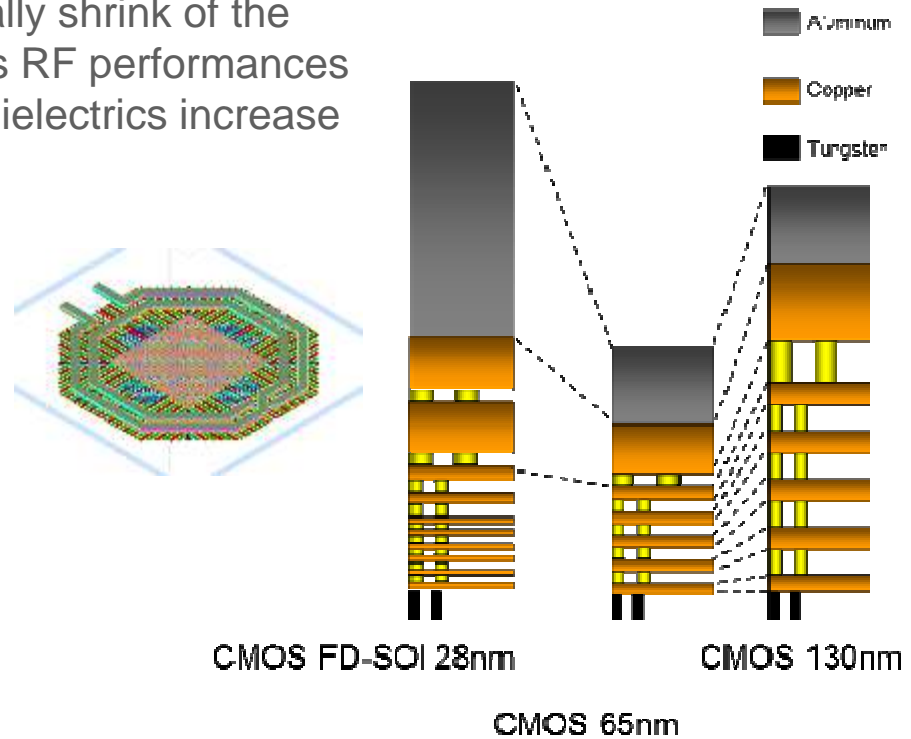
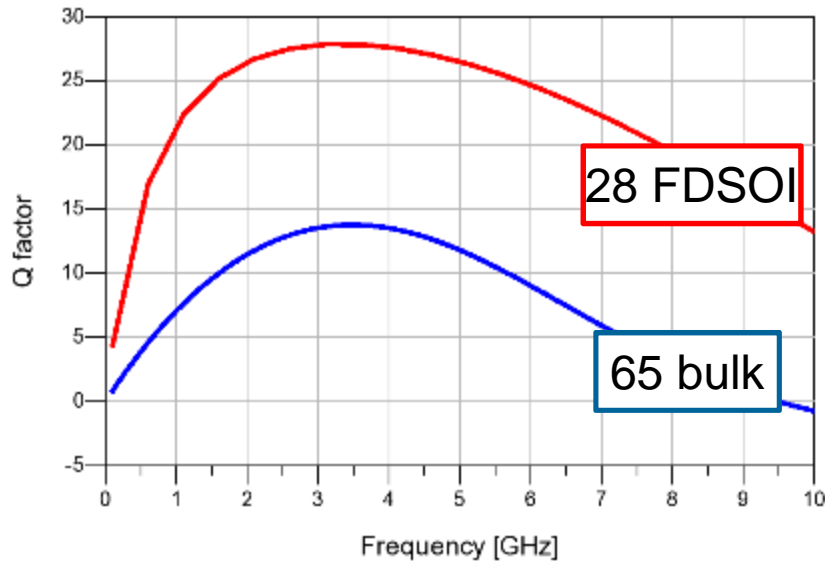


4 dB gain improvement with respect to CMOS 65nm at 2.4GHz

UTBB-FDSOI 28 nm FOR ULTRA LOW POWER RF

- **Passive devices performance**

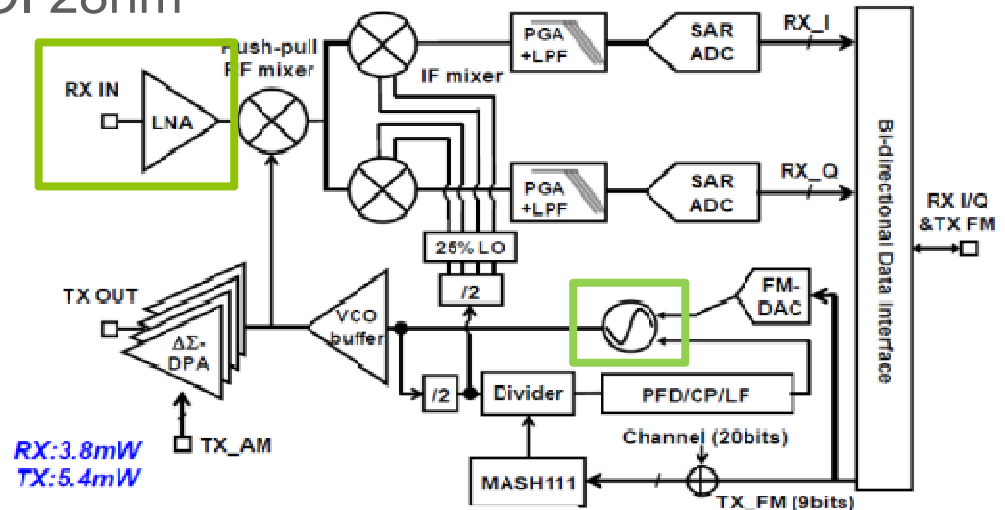
- Typically, the CMOS trend to vertically shrink of the Back-End Of Line (BEOL) penalizes RF performances
- The small metal pitch and the thin dielectrics increase the Resistance/Capacitance ratio



1.5nH inductor offers 25 Q factor value in UTBB-FDSOI 28nm

CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

- Comparison between two usual RF blocs
 - LNA and VCO
- Technology use :
 - CMOS 65 nm : 7metal layers from STMicroelectronics
 - UTBB-FDSOI 28 nm : 10 metal layers from STMicroelectronics
- Transistor models
 - PSP or BSIM for CMOS 65nm
 - UTSOI 2 for UTBB-FDSOI 28nm



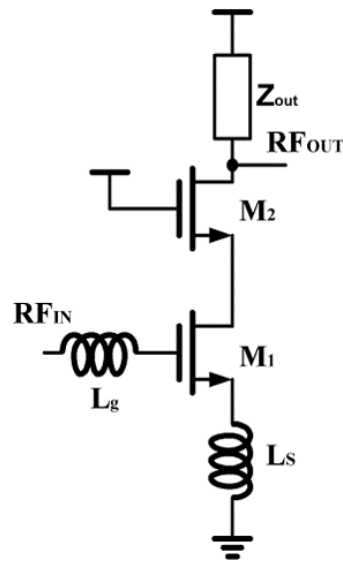
90nm BLE/15.4/15.6 Transceiver

[Y.H. Liu, ISSCC2013]

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CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

LOW NOISE AMPLIFIER : 2.4GHZ TEST CIRCUIT



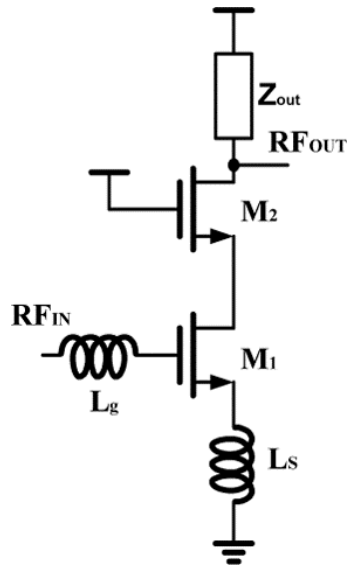
- Degenerated cascode topology
- L_s and L_g inductance used to match noise and input impedance (target $<-10\text{dB } S_{11}$)
- Gain is evaluated considering $Z_{out} = \text{LNA conjugate output impedance}$
- Same inductor Q value (ideal component with set Q factor)

LETI BENCHMARK 2015

	CMOS 65nm	UTBB-FDSOI 28nm
NMOS Family	N-lvt	N-lvt
Inductance Q value	10	10
Nominal Vdd (V)	1.2	1

CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

LOW NOISE AMPLIFIER : 1 mW SCENARIO



LETI BENCHMARK 2015

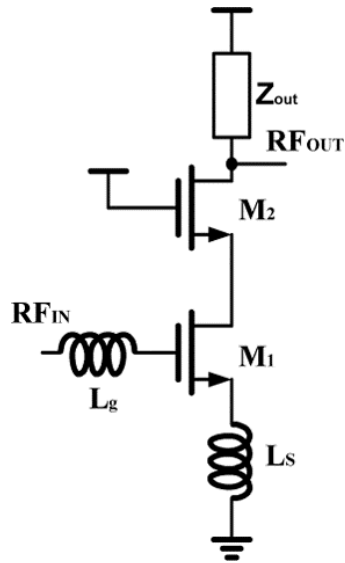
FoM	CMOS 65nm	UTBB-FDSOI 28nm
NFmin (dB)	0.9	0.9
Gain* (dB)	21	25
S11 (dB)	-11	-16
P _{DC} (mW)	1	1
IIP3 (dBm)	-15	-15
ICP1 (dBm)	-24	-24

*Power Gain considering a perfect match output

4dB gain improvement in FD-SOI for same power

CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

LOW NOISE AMPLIFIER : ULTRA LOW-POWER SCENARIO



LETI BENCHMARK 2015

FoM	CMOS 65nm	UTBB-FDSOI 28nm
NFmin (dB)	1	1
Gain (dB)	21	24
S11 (dB)	-10	-10
P _{DC} (mW)	0.4@1.2V	0.1@0.55V*
IIP3 (dBm)	-30	-26
ICP1 (dBm)	-39	-36

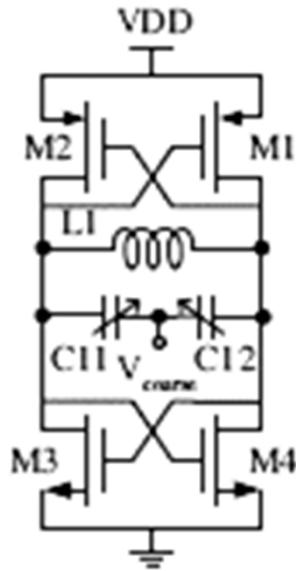
*Using body bias = 350mV

X4 power consumption decrease with same RF performances

CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

TEST CIRCUIT : 2.4GHz

- VCO



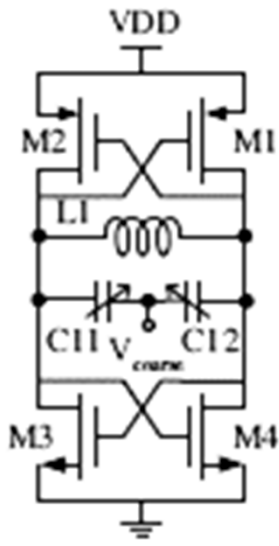
LETI BENCHMARK 2015

- CMOS cross-coupled topology
- Same inductor Q value
 - Ideal component with set Q factor

	CMOS 65nm	UTBB-FDSOI 28nm
NMOS Family	N-lvt / P-lvt	N-lvt / P-lvt
Tank Q value	15	15
Nominal Vdd (V)	1.2	1

CMOS 65 nm vs FDSOI 28nm : RF BENCHMARK

VCO : 1 mW / 0.2 mW SCENARIO



FoM	CMOS 65nm	UTBB-FDSOI 28nm
Frequency (GHz)	2.4	2.4
Phase Noise (1MHz in dBc/Hz)	-119	-126
P_{DC} (mW)	1	1
Phase Noise (1MHz in dBc/Hz)	-105	-117
P_{DC} (mW)	0.2 @ 0.8V	0.2 @ 0.7V

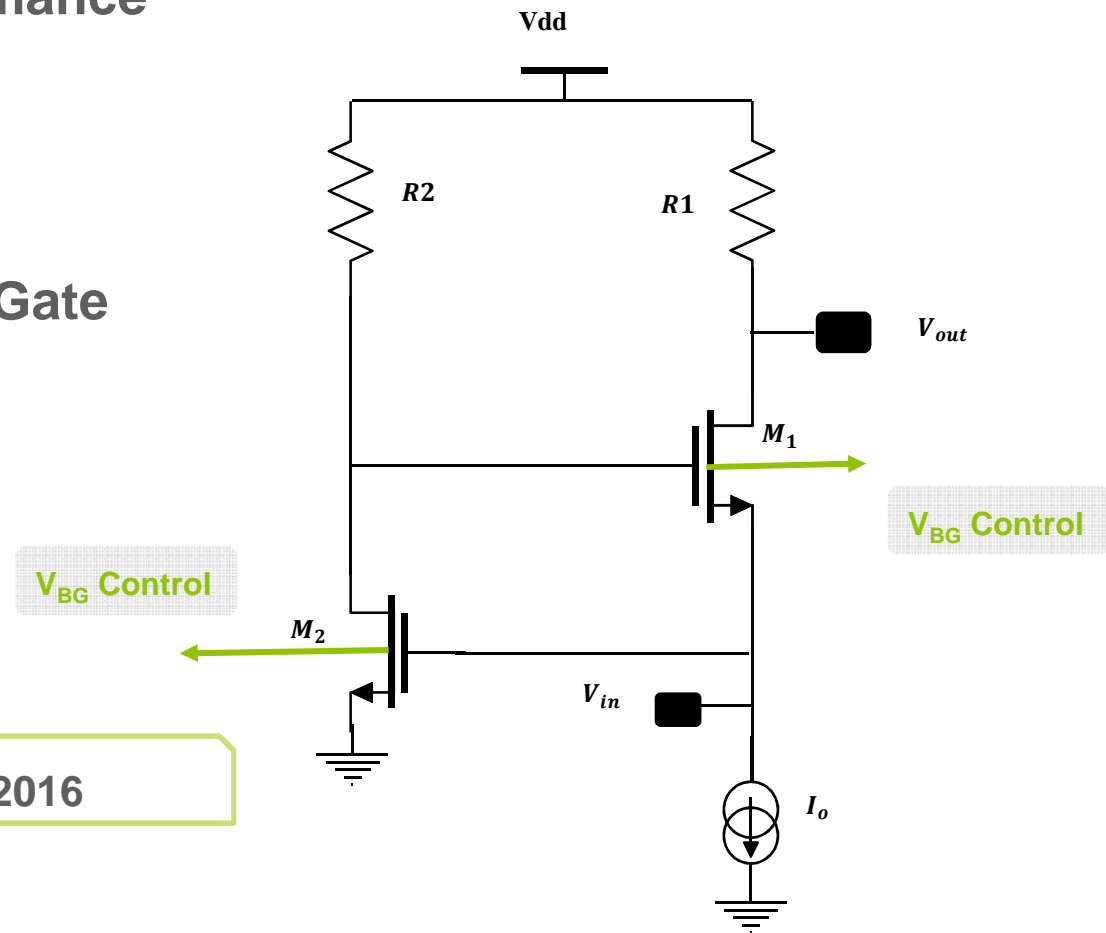
LETI BENCHMARK 2015

7 dB to 12 dB Phase Noise improvement for the same power consumption

SPECIFIC FDSOI BENEFITS FOR LNA

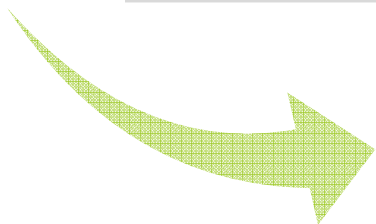
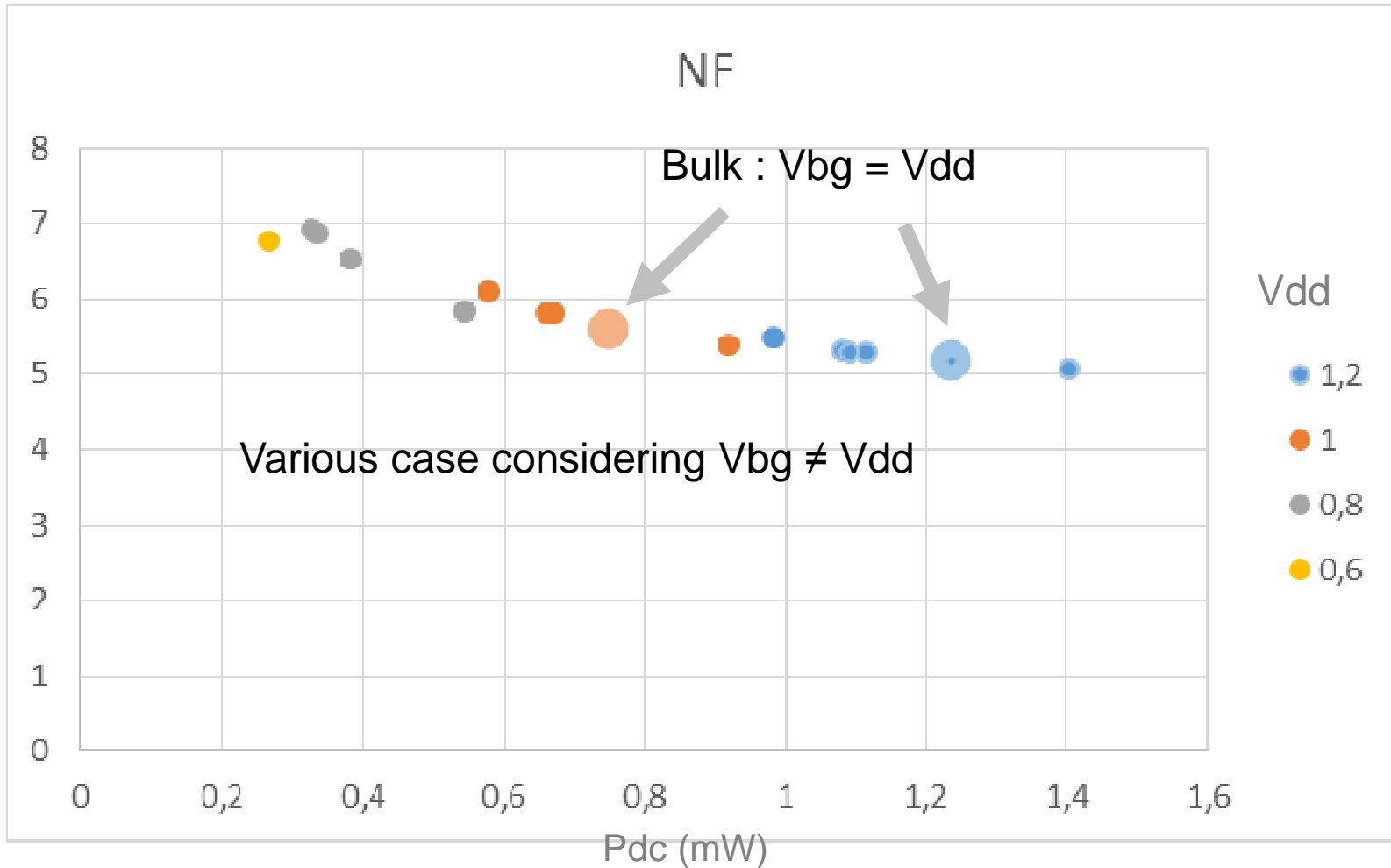
- Evaluation of the performance
 - For the Gain in V (dB)
 - For the NF (dB)

- Making use of the Back-Gate



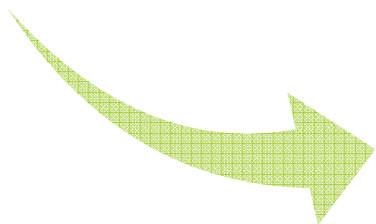
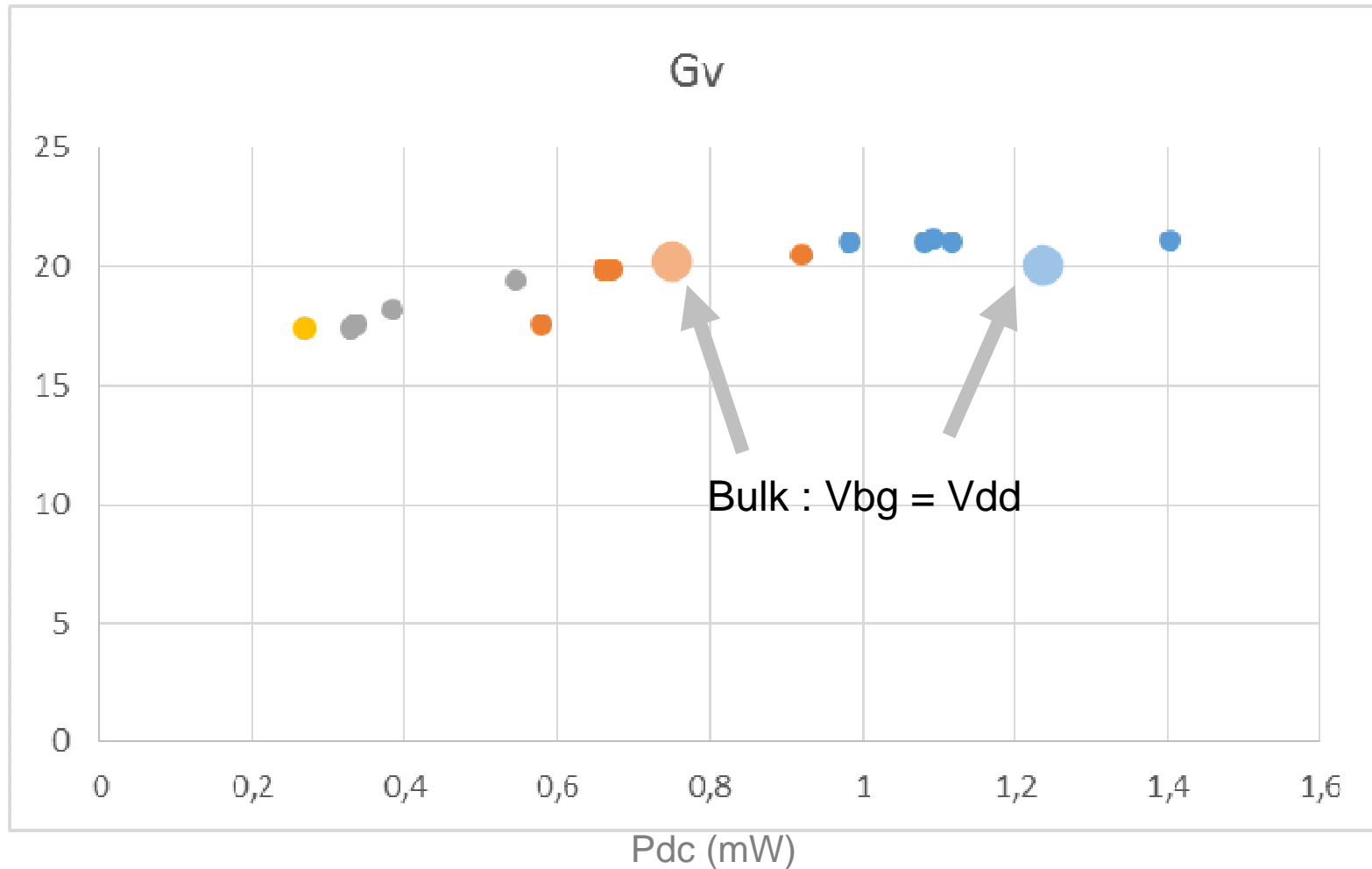
LETI EVALUATION 2015 / 2016

BACK-GATE CONTROL FOR LNA (1/3)



FDSOI : good candidate for ULV use

BACK-GATE CONTROL FOR LNA (2/3)

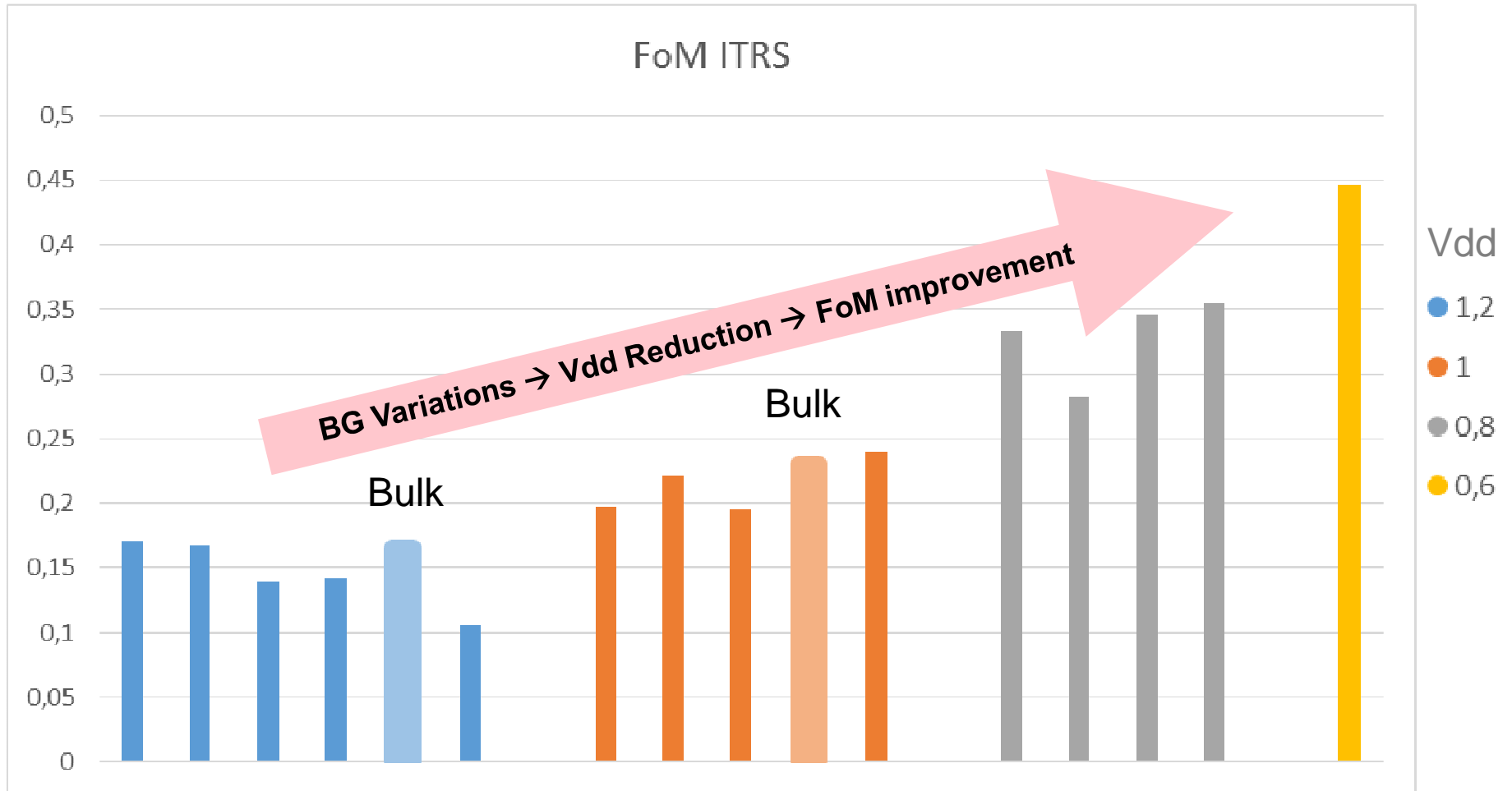


FDSOI : good candidate for reconfigurability

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BACK-GATE CONTROL FOR LNA (3/3)

$$FOM = \frac{Av. freq. IIP3}{(Fmin - 1)(Id. Vdd)}$$



ULP RF – ALWAYS ON / WAKE-UP REALIZATION

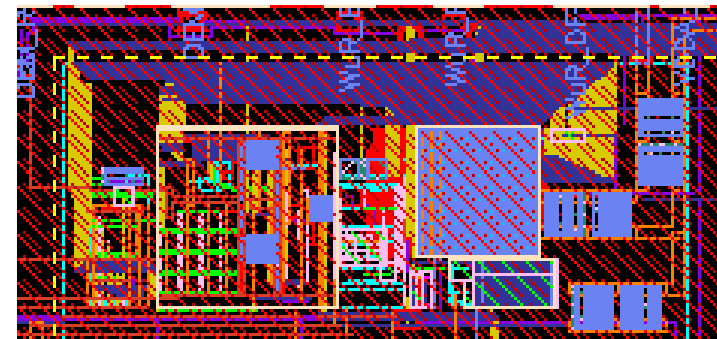
LETI FULL FRONT-END 2016

- **Multi band capability**
 - 868-915 MHz / 1.4 GHz / 2.4 GHz
 - Highly Flexible : Carrier Frequency, Modulation, Channel condition, etc...
 - No costly external component
 - Improved Robustness

- **Adaptive power consumption**
 - Event-driven activity
 - Target to burn ~ **50 μ W in active mode**
 - Analog front-end to demodulation : 20 μ W
 - Synthesizer and LO : 30 μ W

- **Fast power-on time**

- **Low-cost and easy implementation**
 - Inductorless design
 - Calibrationless design
 - FD-SOI 28 nm

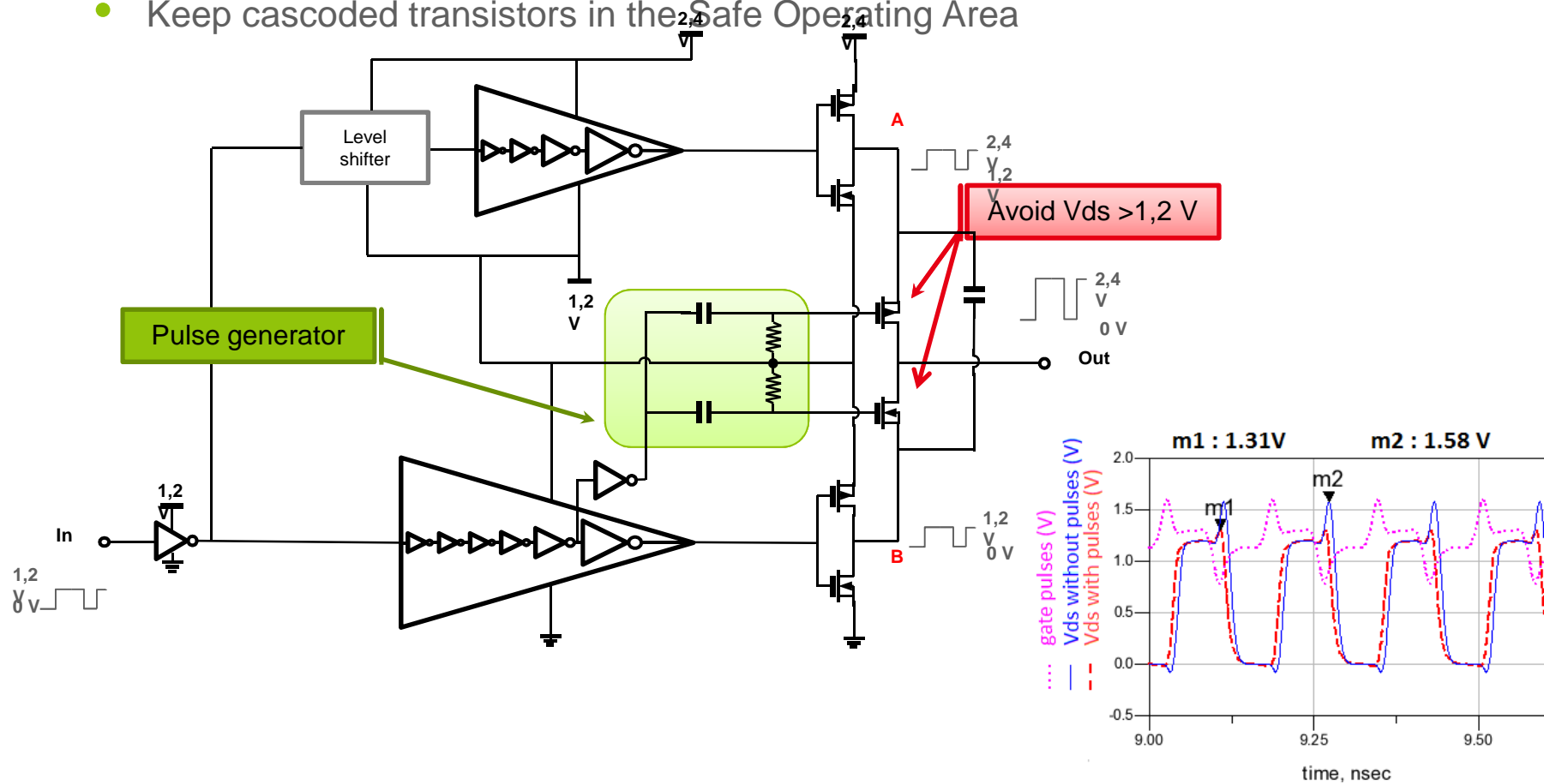


Snapshot of the full Wake-Up RX
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HIGH-SPEED MODULATOR DRIVER - BULK

- **CMOS bulk**

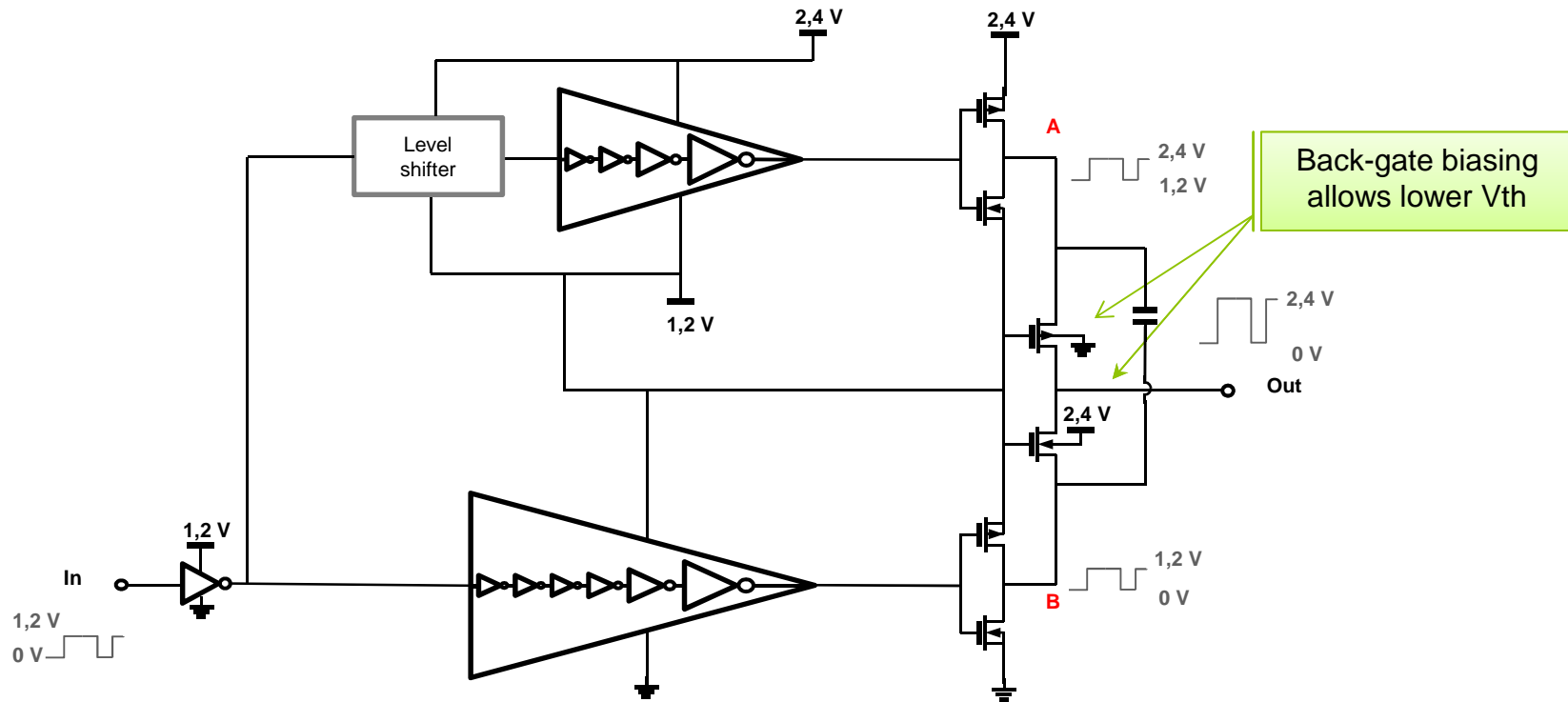
- Additionnal circuitry required
- Keep cascoded transistors in the Safe Operating Area



HIGH-SPEED MODULATOR DRIVER - FDSOI

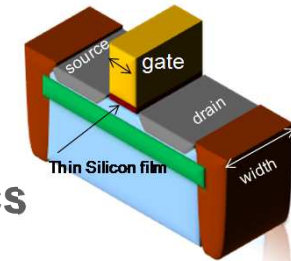
LETI FULL TX/RX 2016

- FDSOI 28 nm
 - Back-Gate allows V_{th} reduction → no V_{ds} over-voltage
 - Very High Speed communications : 25 Gbps



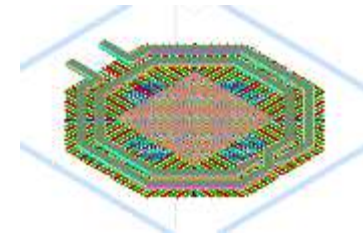
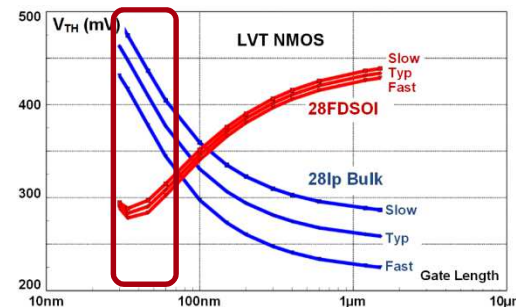


WIRELESS COMMUNICATION : FD-SOI VS BULK



- Gain improvement (no channel doping)
- Higher speed / analog performance / reduced parasitics
- Higher Passive Quality factors (Metal options & reduced S/D cap.)
- Lower power and higher dynamic range / Lower V_{TH}
- Higher frequency operation / faster transistors for lower power
- Easier design / Back Gate as a Static & Dynamic

1 μ m Length	28nmBulk	FDSOI28nm
Gm/Gd	50	300



BETTER GAIN

BETTER PHASE NOISE

ULTRA LOW POWER

FD-SOI RF DESIGN



CURRENT OFFER FROM LETI in FD-SOI

- **ULP RF Front-End : TX and RX**

 - Multi-Standard / Multi-Mode (2016 / 2017)

- **ULP Always-On RX Front-End**

 - Wake-up function / spectrum sensing (2015 / 2016)

- **Very High Speed Optical Driver / Modulator / Receiver**

 - Increase speed rate to tackle the 56 Gbps (2016)

- **Fast & High-Resolution ADC : 100 MSps / 12 bits**

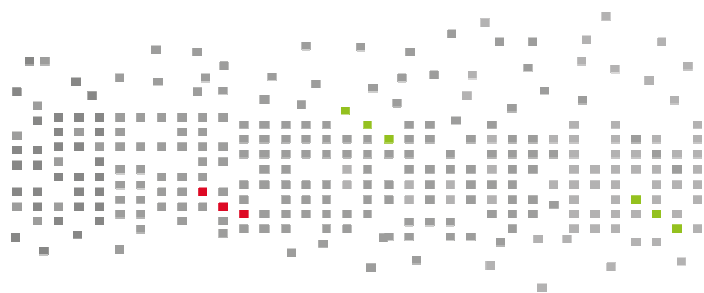
 - General purpose / Low Power for RF Front-End (2016 / 2017)

ULP RF for IoT

Very High Speed OPTICAL
DRIVER/RECEIVER

High Sampling Rate ADC

FD-SOI RF DESIGN



Leti, technology research institute

Commissariat à l'énergie atomique et aux énergies alternatives
Minatec Campus | 17 rue des Martyrs | 38054 Grenoble Cedex | France
www.leti.fr

